Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	"156"/$.ccls. and (anisotropical near1 tape) and (cut or "cut-off") and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:27
L2	0	"156"/$.ccls. and (anisotropical near1 tape) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:27
L3	0	"156"/$.ccls. and (anisotropical near2 tape) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:27
L4	0	"156"/$.ccls. and (anisotropical near3 tape) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:27
L5	0	"156"/$.ccls. and (anisotropical near3 tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L6	18	"156"/$.ccls. and (anisotropic near3 tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L7	0	"83"/$.ccls. and (anisotropic near3 tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L8	24	"29"/$.ccls. and (anisotropic near3 tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L9	477	(156/353).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28

L10	501	(156/359).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L11	268	(156/360).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L12	1	matsushita.asn. and (anisotropical near3 tape) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L13	52	matsushita.asn. and (anisotropic near3 tape) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L14	769	(156/378).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L15	219	(156/379).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L16	0	"83"/$.ccls. and (TCP) and (cut or "cut-off") and (measure or measurement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L17	2484	"83"/$.ccls. and (cut or "cut-off") and (measure or measurement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L18	161	"83"/$.ccls. and (cut or "cut-off") and (measure or measurement) and (tape or film) and (circuit or electrode)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28

L19	0	(anisotropical near3 tape) and conductive and (cut or "cut-off") and (measure or measurement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L20	29	(anisotropic near3 tape) and conductive and (cut or "cut-off") and (measure or measurement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L21	348	(TCP) and conductive and (cut or "cut-off") and (measure or measurement)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L22	173	(TCP) and conductive and (cut or "cut-off") and (measure or measurement) and (adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L23	0	"83"/$.ccls. and (TCP or "tape carrier package") and ((temperature or thermal) near2 (compensation or comparation or measurement))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L24	7	"156"/$.ccls. and (TCP or "tape carrier package") and ((temperature or thermal) near2 (compensation or comparation or measurement))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L25	1	"29"/$.ccls. and (TCP or "tape carrier package") and ((temperature or thermal) near2 (compensation or comparation or measurement))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L26	100	(118/677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L27	906	(156/521).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L28	0	"156"/$.ccls. and (semiconductor same tape) and (temperature near4 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28

L29	281	(156/367).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 22:33
L30	0	"156"/$.ccls. and (semiconductor same tape) and (size near4 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L31	0	"156"/$.ccls. and (semiconductor same tape) and (size near4 correction)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L32	0	"156"/$.ccls. and (semiconductor same tape) and (temperature same compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L33	0	"156"/$.ccls. and (semiconductor near20 tape) and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L34	0	"83"/$.ccls. and (semiconductor near20 tape) and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L35	1	"29"/$.ccls. and (semiconductor near20 tape) and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L36	0	"29"/$.ccls. and (TCP or "tape carrier package") and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L37	44	"29"/$.ccls. and (adhesive) and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L38	22	"156"/$.ccls. and (adhesive) and (temperature near20 compensation) and (tape or film)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28

L39	216	(29/835).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L40	24	"29"/$.ccls. and (TAB or (tape and attach$5 and bond$4)) and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L41	10	"156"/$.ccls. and (TAB or (tape and attach$5 and bond$4)) and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L42	1	"83"/$.ccls. and (TAB or (tape and attach$5 and bond$4)) and (temperature near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L43	428	(29/833).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L44	1	"156"/$.ccls. and (TAB or (tape and attach$5 and bond$4)) and (deformation near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:50
L45	0	"83"/$.ccls. and (TAB or (tape and attach$5 and bond$4)) and (deformation near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L46	1	"29"/$.ccls. and (TAB or (tape and attach$5 and bond$4)) and (deformation near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L47	129	matsushita.asn. and (ACF)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28

L48	89	(83/75.5).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L49	113	(83/76.4).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L50	406	(83/364).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L51	0	"118"/$.ccls. and (adhesive near3 dispens$4) and (deformation near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L52	0	"118"/$.ccls. and (adhesive near3 dispens$4) and (size near20 comparation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L53	1	"118"/$.ccls. and (adhesive near3 dispens$4) and (size near20 compensation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L54	0	"118"/$.ccls. and (adhesive near3 dispens$4) and (size near20 comparision)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L55	9	fuji.asn. and (ACF)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L56	3	fuji.asn. and (anisotropic near3 tape) and conductive	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28

L57	58	(700/303).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L58	193	(700/302).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L59	0	"700"/$.ccls. and (adhesive near3 dispens$4) and (size near20 comparision)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L60	0	"702"/$.ccls. and (adhesive near3 dispens$4) and (size near20 comparision)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L61	0	"700"/$.ccls. and (anisotropical near3 tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L62	104	(702/97).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L63	372	(702/158).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L64	112	(702/101).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 21:28
L65	18	"118"/$.ccls. and ciardella	USPAT	OR	OFF	2004/10/11 21:28
L66	0	"700"/$.ccls. and (adhesive near3 dispens$4) and (size near20 comparison)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28

L67	0	"702"/$.ccls. and (adhesive near3 dispens$4) and (size near20 comparison)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L68	6	"700"/$.ccls. and (adhesive near3 dispens$4) and (size near20 control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L69	3	"702"/$.ccls. and (adhesive near3 dispens$4) and (size near20 control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L70	4	"702"/$.ccls. and (adhesive near3 dispens$4) and (location near20 control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 22:04
L71	9	"700"/$.ccls. and (adhesive near3 dispens$4) and (location near20 control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L72	29	"118"/$.ccls. and (adhesive near3 dispens$4) and (location near20 control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L73	42	"156"/$.ccls. and (adhesive near3 dispens$4) and (location near20 control)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L74	0	"118"/$.ccls. and (resin near3 dispens$4) and (location near20 weight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L75	0	"118"/$.ccls. and (ACF near3 dispens$4) and (location near20 weight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L76	6	"118"/$.ccls. and (adhesive near3 dispens$4) and (location near20 weight)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28

L77	0	"118"/$.ccls. and (adhesive near3 dispens$4) and (location near20 mass)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L78	0	"118"/$.ccls. and (adhesive near3 dispens$4) and (leadframe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L79	19	"118"/$.ccls. and (leadframe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 21:28
L80	82	"156"/$.ccls. and (leadframe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 22:07

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1331	(156/64).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01
L2	407	(156/358).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01
L3	281	(156/367).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 20:45
L4	137	(156/368).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 20:41
L5	984	(156/361).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01
L6	769	(156/378).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01
L7	1	("5564183").PN.	USPAT; USOCR	OR	OFF	2004/10/11 19:01
L8	219	(156/379).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01

L9	8	(((156/64).CCLS.) ((156/353).CCLS.) ((156/358).CCLS.) ((156/359).CCLS.) ((156/360).CCLS.) ((156/361).CCLS.) ((156/367).CCLS.) ((156/368).CCLS.) ((156/378).CCLS.) ((156/379).CCLS.)) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	USPAT	OR	ON	2004/10/11 19:01
L10	4	(((156/64).CCLS.) ((156/353).CCLS.) ((156/358).CCLS.) ((156/359).CCLS.) ((156/360).CCLS.) ((156/361).CCLS.) ((156/367).CCLS.) ((156/368).CCLS.) ((156/378).CCLS.) ((156/379).CCLS.)) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L11	63	("29"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L12	42	("156"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L13	81	("438"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 20:31
L14	32	("700"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L15	61	("702"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01

L16	477	(156/353).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01
L17	501	(156/359).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01
L18	268	(156/360).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/11 19:01
L19	5	(((156/361).CCLS.)) and ((circuit or chip or semicondutor or die or electrode)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L20	9	(((156/378).CCLS.)) and ((circuit or chip or semicondutor or die or electrode)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L21	70	("29"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L22	18	("156"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L23	124	("438"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L24	11	("700"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01

L25	22	("702"/$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 19:01
L26	12	"5564183"	USPAT	OR	OFF	2004/10/11 19:01
L27	2	(("6023666") or ("5711989")).PN.	USPAT	OR	OFF	2004/10/11 19:33
L28	182	((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration)) and (anisotropy or anisotropic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/11 20:31